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In the claims:

1-44 (canceled)

45. (previously presented) A polishing pad for chemical mechanical polishing a semiconductor wafer comprising:

a polishing surface having a first wear rate during polishing;

a window portion formed in the polishing pad and having a window surface formed flush with the polishing surface; and

wherein the window surface has a second wear rate during polishing greater than the first wear rate.

46. (previously presented) The polishing pad of claim 45, wherein the second wear rate is 5% to 25% greater than the first wear rate.

47. (previously presented) The polishing pad of claim 45, wherein the window portion includes a polymerized blend of two immiscible polymers.

48. (previously presented) The polishing pad of claim 45, wherein the window portion includes at least one of polymethylmethacrylate and polycarbonate.

49. (previously presented) The polishing pad of claim 45, wherein the window portion includes a polymer matrix having discontinuities formed therein that act to increase the wear rate of the polymer matrix without significantly contributing to light scattering.

50. (previously presented) The polishing pad of claim 49, wherein the discontinuities include at least one selected from the group of discontinuities comprising: solid particles, fluids, gases and immiscible polymers.

51. (previously presented) The polishing pad of claim 49, wherein the discontinuities include solid matter having a lower resistance to wear than the polymer matrix.

52. (previously presented) The polishing pad of claim 51, wherein the solid matter includes at least one type of solid particles selected from the group of particles comprising: silica, titania, alumina, ceria, and plastic.

53. (new) An apparatus for polishing a wafer comprising:

- a polishing pad having a surface and a first wear rate during polishing;

- a window portion formed in the polishing pad and having a surface formed flush with the polishing pad surface;

- wherein the window portion has a second wear rate during polishing equal to or greater than the first wear rate so that the window surface remains flush with the polishing pad surface during polishing; and

- wherein the second wear rate is 5% to 25% greater than the first wear rate.

54. (new) An apparatus for polishing a wafer comprising:

- a polishing pad having a surface and a first wear rate during polishing;

- a window portion formed in the polishing pad and having a surface formed flush with the polishing pad surface;

- wherein the window portion has a second wear rate during polishing equal to or greater than the first wear rate so that the window surface remains flush with the polishing pad surface during polishing; and

- wherein the window portion includes a polymer matrix having discontinuities formed therein that act to increase the wear rate of the polymer matrix without significantly contributing to light scattering.

55. (new) The apparatus of claim 54, wherein the discontinuities include at least one selected from the group of discontinuities comprising: solid particles, fluids, gases and immiscible polymers.

56. (new) The apparatus of claim 55, wherein the discontinuities include solid matter having a lower resistance to wear than the polymer matrix.

57. (new) The apparatus of claim 56, wherein the solid matter includes at least one type of solid particles selected from the group of particles comprising: silica, titania, alumina, ceria, and plastic.

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